508310171 01/02/2024

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT8357364

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
INSTITUTE OF CHEMISTRY CHINESE ACADEMY OF SCIENCES	11/27/2023

RECEIVING PARTY DATA

Name:	INNOVATIVE SEMICONDUCTOR SUBSTRATE TECHNOLOGY CO., LTD.	
Street Address:	ROOM O-2-146, NO.25, HUAYUAN NORTH ROAD	
Internal Address:	HAIDIAN DISTRICT	
City:	BEIJING	
State/Country:	CHINA	
Postal Code:	100083	

PROPERTY NUMBERS Total: 2

Property Type	Number
Patent Number:	11726309
Application Number:	17043615

CORRESPONDENCE DATA

Fax Number: (216)348-5474

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2163485400

Email: ipmailbox@mcdonaldhopkins.com

Correspondent Name: MCDONALD HOPKINS LLC **Address Line 1:** 600 SUPERIOR AVE., E.

Address Line 2: SUITE 2100

Address Line 4: CLEVELAND, OHIO 44114

ATTORNEY DOCKET NUMBER: 37399-00406

NAME OF SUBMITTER: DAVID B. CUPAR

SIGNATURE: /David B. Cupar/

DATE SIGNED: 01/02/2024

Total Attachments: 2

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PATENT 508310171 REEL: 065991 FRAME: 0605

BOIP Ref.: BY23EX2440NNPE-US MH Ref.: 37399-00406

ASSIGNMENT AGREEMENT

This Assignment Agreement (the "Agreement") is made and entered into as of [Date] (the "Effective Date"), by and between:

Assignor:

<u>INSTITUTE OF CHEMISTRY CHINESE ACADEMY OF SCIENCES</u>, a corporation organized and existing under the laws of [State/Country], with its principal place of business at NO. 2 NORTH 1ST STREET ZHONGGUANCUN, HAIDIAN DISTRICT BEIJING, CHINA 100190 (hereinafter referred to as "Assignor"),

and

Assignee:

INNOVATIVE SEMICONDUCTOR SUBSTRATE TECHNOLOGY CO., LTD., a corporation organized and existing under the laws of CHINA with its principal place of business at Room O-2-146, No.25, Huayuan North Road, Haidian District, Beijing, 100083, China (hereinafter referred to as "Assignee").

Collectively referred to as the "Parties."

WHEREAS, Assignor is the owner and holder of all intellectual property rights, title, and interest in and to US Patent No. 11,726,309 (the "Patent"), granted on August 15, 2023;

WHEREAS, Assignor desires to assign and transfer all its rights, title, and interest in the Patent to Assignee;

WHEREAS, Assignee desires to acquire all the rights, title, and interest in the Patent from Assignor;

NOW, THEREFORE, in consideration of the mutual covenants and promises contained herein, and for other good and valuable consideration, the sufficiency of which is hereby acknowledged, the Parties agree as follows:

1. Assignment of Intellectual Property Rights:

Assignor hereby assigns, transfers, and conveys to Assignee all of its rights, title, and interest in and to the Patent, including all associated rights, benefits, and privileges.

2. Consideration:

In consideration for the assignment, Assignee shall pay to Assignor the agreed-upon consideration as specified in a separate agreement between the Parties.

3. Warranties:

a) Assignor represents and warrants that it is the legal and beneficial owner of the Patent, and has the full right, power, and authority to assign the same to Assignee.

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b) Assignor further represents and warrants that, to the best of its knowledge, the Patent is valid and enforceable, and has not been subject to any encumbrances, licenses, or claims adverse to Assignor's ownership rights.

4. Further Assurances:

Assignor agrees to execute any and all documents, perform any acts, and provide any assistance reasonably necessary to evidence, perfect, and protect Assignee's rights in the assigned intellectual property.

5. Governing Law and Jurisdiction:

This Agreement shall be governed by and construed in accordance with the laws of the United States of America. Any disputes arising out of or in connection with this Agreement shall be submitted to the exclusive jurisdiction of the courts of the United States of America.

6. Entire Agreement:

This Agreement constitutes the entire agreement between the Parties relating to the subject matter hereof and supersedes all prior agreements, understandings, and negotiations, whether oral or written, with respect thereto.

IN WITNESS WHEREOF, the Parties hereto have executed this Assignment Agreement as of the Effective Date first above written.

Assignor:

INSTITUTE OF CHEMISTRY CHINESE ACADEMY OF SCIENCES

By: 1853 November 27. 2013

Name: FU, Dongsheng

Title: Deputy Director of Science and Technology

Assignee:

INNOVATIVE SEMICONDUCTOR SUBSTRATE TECHNOLOGY CO., LTD.

By: 1912 November 24, 2023

Name: MU, Fengwen Title: General Manager

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PATENT REEL: 065991 FRAME: 0607

RECORDED: 01/02/2024